

MECHANICAL CASE OUTLINE

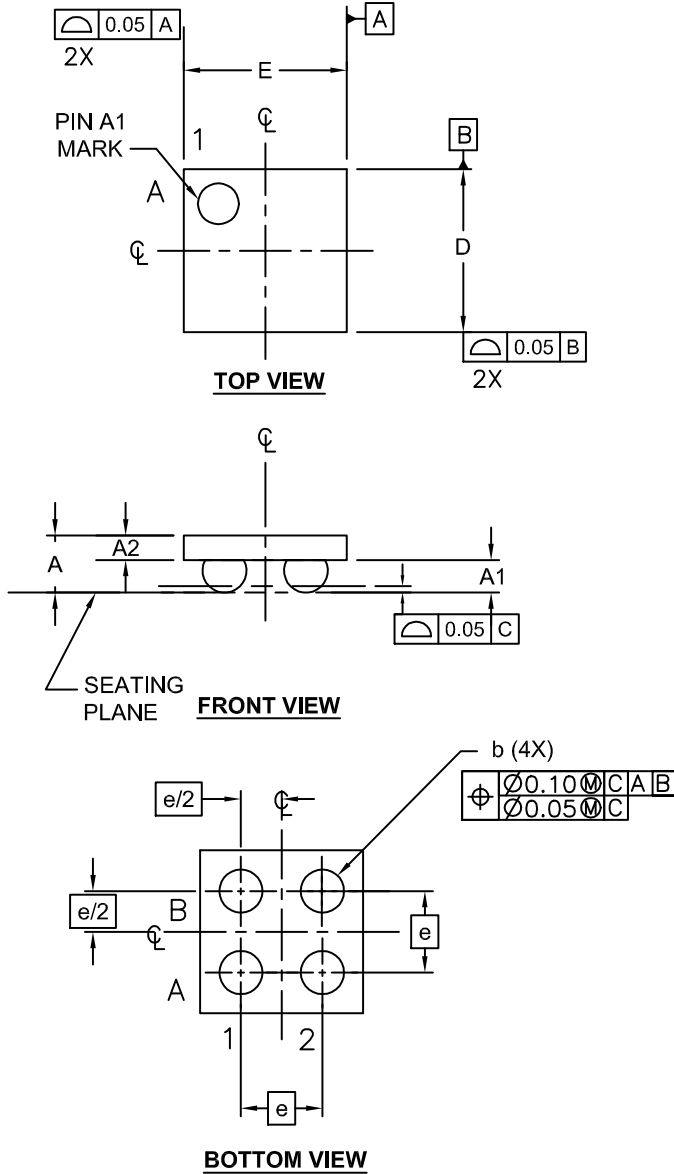
PACKAGE DIMENSIONS

ON Semiconductor®



WLCSP4 1x1x0.4
CASE 567PS
ISSUE A

DATE 30 JUL 2021



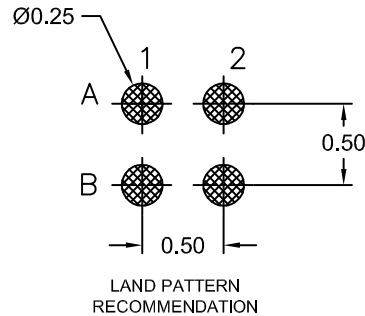
NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE IS NOT PRESENTLY REGISTERED WITH ANY STANDARDS COMMITTEE.
- B) DIMENSIONS ARE IN MILLIMETERS.
- C) DRAWING CONFORMS TO ASME Y14.5M-1994
- D) TERMINAL CONFIGURATION TABLE:

GATE	SOURCE	DRAIN
A1	A2, B2	B1

E) DRAWING FILENAME: MKT-UC004ADREV2

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	-	-	0.40
A1	0.00	-	0.235
A2	0.125	0.15	0.162
b	0.24	0.265	0.29
D	0.95	1.00	1.05
e	0.50 BSC		
e/2	0.25 BSC		



*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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